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(54) **EMI INHIBITION MULTILAYERED PRINTED BOARD**

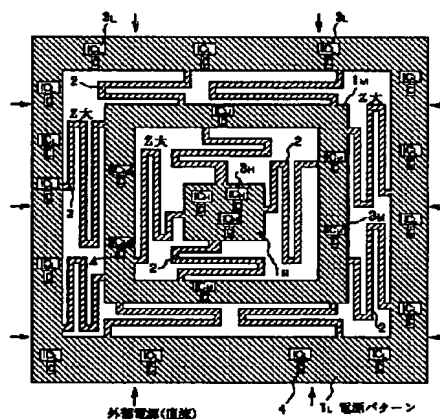
source wiring pattern 2.

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(57) Abstract:

PROBLEM TO BE SOLVED: To provide a multilayered printed board on which a plurality of circuit elements such as IC, LSI, etc., are mounted and by which space can be saved and electromagnetic noises be also eliminated greatly.

SOLUTION: Circuit elements to be mounted on are classified into high-speed IC/LSI3H, medium-speed IC/LSI3H and low-speed IC/LSI3L according to their operating speed. A power source layer of a multilayered printed board is classified into power source patterns 1H, 1M and 1L for high-speed, medium speed and low-speed according to the respective high-speed, medium-speed and low-speed IC/LSI3H, 3M and 3L, and the respective power source patterns 1H, 1M and 1L are connected mutually by a power source wiring pattern 2 as to separate them in high frequency. The respective IC/LSI3H, 3M and 3L are connected with a decoupling capacitor 4, and further insulation layers on the upper and lower sides of the power source layer is formed of insulation material mixed with a magnetic body to improve a high-frequency impedance Z of the power



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